502753175 04/03/2014

PATENT ASSIGNMENT COVER SHEET

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 SUBMISSION TYPE:
 NEW ASSIGNMENT

 NATURE OF CONVEYANCE:
 ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SZU-YING CHEN	03/28/2014
DUN-NIAN YAUNG	03/28/2014

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company		
Street Address:	No. 8, Li-Hsin Rd. 6		
Internal Address:	Science-Based Industrial Park		
City:	Hsin-Chu		
State/Country:	TAIWAN		
Postal Code:	300-77		

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14229159

CORRESPONDENCE DATA

Fax Number: (972)732-9218

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via

US Mail.

Phone: 972-732-1001

Email:docketing@slater-matsil.comCorrespondent Name:SLATER & MATSIL, L.L.P.Address Line 1:17950 PRESTON ROAD

Address Line 2: SUITE 1000

Address Line 4: DALLAS, TEXAS 75252

ATTORNEY DOCKET NUMBER: TSM13-1307

NAME OF SUBMITTER: SHERRY L. COLGROVE

SIGNATURE: /Sherry L Colgrove/

DATE SIGNED: 04/03/2014

Total Attachments: 1

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PATENT 502753175 REEL: 032598 FRAME: 0745

ATTORNEY DOCKET NO. TSM13-1307

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Talwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of TW, with its principal office at No. 8, LI-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu 300-77, TW, is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Uniform-Size Bonding Patterns		
SIGNATURE OF INVENTOR AND NAME	Szurying Chen	Dun-Nian Yaung	
DATE	7014/3/28	V 214.3.7	
RESIDENCE	Toufen Township, Taiwan	Taipei City, Taiwan	

TSM13-1307 Page 1 of 1 Assignment

RECORDED: 04/03/2014

PATENT REEL: 032598 FRAME: 0746